SHARP MICROELECTRONICS OF THE AMERICAS

Product Change Notification

Type of Notification: Production Location Change

ISSUE DATE	TRANSITION DATE	NOTIFICATION NO.
17 July 2007	See Table, below.	PCN-20070717-01

This is to advise you that the following products have been changed.

Product ID (Description):

Optoelectronics and Power Devices (Please see Type and Typical Part Number descriptions in the Table.)

Description of Change:

The parts represented in the Table below will have their production locations changed and in some cases additional production capability added to allow for upgrading and consolidating of assembly lines. This is a running change to production, taking place beginning on the dates shown in the Table.

There is no effect upon reliability, quality, mechanical, electrical, or RoHS specifications.

Effect of Change:

Sharp is shifting production of some Optoelectronics and Power Device parts to different production locations; in some cases adding additional production capacity. Sharp continues to manage quality at these locations, therefore there is no consequential effect upon reliability, quality, mechanical, electrical, or RoHS specifications.

TYPE	TYPICAL P/N	PROCESS	NOW	POST-CHANGE	TIME-FRAME
Conventional PC400 Series	PC400J00000F	All: Chip Mount to Packing	Sun-S (Kannabe)	SSI	Aug. 2007
Dust sensor	GP2Y1010AU0F	All: Chip Mount to Packing	FITC	SSI	Sep. 2007
Frame Type IRDA	GP2W0110VY05	All: Chip Mount to Packing	FITC	Chubu (Ensei)	June 2007
GA220 Series	GA220T2L1IZ	All: Chip Mount to Packing	Fujimoto (Ise)	FITC	July 2007
GL450 Series	GL453SE0000F	All: Chip Mount to Packing	Sun-S (Kannabe)	FITC	Oct. 2007
GP1S092/093/094/ 096/097 Series	GP1S093HCZ0F	Chip Mount to First Mold	Chubu (Shingu)	Chubu (Ensei)	Dec. 2007
GP1S196 Series	GP1S196HCZ0F	All: Chip Mount to Packing	Chubu (Shingu)	Chubu (Ensei)	Sep. 2007
GP2A25 Series	GP2A25J0000F	All: Chip Mount to Packing	Chubu (Shingu)	Chubu (Ensei) (Added)	July 2007
GP2S29 Series	GP2S29SJ000F	Chip Mount to First Mold	Chubu (Shingu)	Chubu (Ensei)	Feb. 2008
High Performance Encoder Elements	Element for GP1A042RBA0F	All: Chip Mount to Packing	Chubu (Shingu)	Chubu (Ensei) Added	Oct. 2007
IS1623 Series	IS1623Q	All: Chip Mount to Packing	Fujimoto (Ise)	FITC	July 2007
IS45 Series	IS450E/456E	All: Chip Mount to Packing	Takemoto	Fujimoto (Ise) (FITC)	July 2007
PC400X Series	SOP8-PIN: PC412S0NIP0F	All: Chip Mount to Packing	Sun-S (Kannabe)	Sun-S (Wuxi)	Oct. 2007
PC814/844/847 Series	PC814X1J000FP Q847XJ0000F	All: Chip Mount to Packing	Sun-S (Kannabe)	Sun-S (Kannabe)	Aug. 2007

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PC922 Series	PC923L0NIP0F	All: Chip Mount to Packing	Sun-S (Kannabe)	Sun-S (Konzan)	Dec. 2007
PC928/929 Series	PC929J00000F	All: Chip Mount to Packing	Sun-S (Kannabe)	Sun-S (Wuxi)	Dec. 2007
SC-63 Regulators (NEW)	PQ200WNA1ZPH	All: Chip Mount to Packing	Fujimoto (Kochi) SSI	FITC (Added)	July 2007
SC-63 Regulators: 3 pin, Sleeve, Laser/ Ink mark only, moisture proof package	PQ05SZ1UJ00H	All: Chip Mount to Packing	Fujimoto (Kochi)	SSI	Mar. 2008
SOT-23-5 Series	PQ1X331M2ZPH	All: Chip Mount to Packing	Sun-S (Kannabe)	SSI	Dec. 2007
SOT-23L Series Regulators	PQ1K333M2ZPH	All: Chip Mount to Packing	Sun-S (Kannabe)	SSI	Dec. 2007
SSR	PR23MF11NSZF	All: Chip Mount to Packing	Sun-S (Kannabe)	Sun-S (Konzan)	Dec. 2007
SSR	S102S01F	All: Chip Mount to Packing	Fujimoto (Kochi)	SSI	June 2008
Tilt Sensor	GP2A222HCKA6	Chip Mount to First Mold	Chubu (Shingu)	Chubu (Ensei)	Oct. 2007
TO220 Regulators	PQ1CG2032FZH	All: Chip Mount to Packing	Fujimoto (Kochi)	SSI	July 2007
TO220-N5 Regulators	PQ5EV3J0000H	All: Chip Mount to Packing	Fujimoto (Kochi)	SSI	Mar. 2008
TO263 Regulators	PQ1CY1032ZPH	All: Chip Mount to Packing	Fujimoto (Kochi)	FITC (Added)	July 2007

Suggested Alternate Parts and/or Manufacturers:

OBSOLETED SHARP PART NO.	SUGGESTED ALTERNATE PART NO.	ALTERNATE MANUFACTURER
N/A	N/A	N/A

In case of further questions, please contact your Sharp sales representative.

Customer Acknowledgement of receipt of Product Notification.

Acceptance:

Name: Title:

Company: Date: